

Claims:

1. An EMI-attenuating ventilation panel for an electronic device enclosure, comprising:
  - an electronically conductive base plate; and
  - a plurality of first vents and second vents alternatively defined in the base plate, each of the first vents having two first sidewalls integrally extending from the base plate on opposite sides thereof, each of the second vents having two second sidewalls integrally extending from the base plate on opposite sides thereof and perpendicular to said first sidewalls, the first and second vents cooperatively forming a vent array;wherein each of the first and second vents in an inner portion of the array is surrounded by corresponding first sidewalls and second sidewalls.
2. The EMI-attenuating air ventilation panel as claimed in claim 1, wherein both the first sidewalls and the second sidewalls are perpendicular to the base plate.
3. An EMI-attenuating air ventilation panel for an electronic device enclosure, comprising:
  - an electronically conductive base plate; and
  - a plurality of polygonal vents defined in the base plate, each of the vents having a plurality of sidewalls extending from respective sides thereof.
4. The EMI-attenuating air ventilation panel as claimed in claim 3, wherein the sidewalls slantwisely and inwardly extend from respective sides of each of the vents and define a smaller upper opening therebetween.
5. The EMI-attenuating air ventilation panel as claimed in claim 3, wherein the vents comprises alternately arranged first vents and second vents.
6. The EMI-attenuating air ventilation panel as claimed in claim 5, wherein each of the first vents comprises two first sidewalls oriented parallel to a first axis, and each of the second vents comprises two second sidewalls oriented parallel to a second axis that is perpendicular to the first axis.

7. The EMI-attenuating air ventilation panel as claimed in claim 6, wherein each of the first and second vents in an inner portion of the base plate is surrounded by corresponding first sidewalls and second sidewalls.
8. The EMI-attenuating air ventilation panel as claimed in claim 3, wherein the polygonal vents are hexagon vents and the sidewalls are stamped from the base plate adjacent spaced three edges of the vents, respectively.
9. The EMI-attenuating air ventilation panel as claimed in claim 8, wherein each of the hexagon vents in an inner portion of the base plate is surrounded on spaced three sides by three sidewalls formed therein and surrounded on the other three sides by three sidewalls formed in three adjacent vents, respectively.
10. The EMI-attenuating air ventilation panel as claimed in claim 3, wherein for each of said polygonal vents, not all the sides have the corresponding side walls extending therefrom, respectively.
11. The EMI-attenuating air ventilation panel as claimed in claim 10, wherein for each of said polygonal vents, the corresponding side walls are alternately arranged for at least every two adjacent two sides thereof.
12. The EMI-attenuating air ventilation panel as claimed in claim 10, wherein for each of said polygonal vents, an EMI shielding can be achieved by not only the side walls extending from the corresponding sides thereof, but also the corresponding side walls of the neighboring vents which are located beside the other sides having no side walls extending therefrom.
13. An electronic device enclosure comprising:
  - a casing; and
  - at least one EMI-attenuating air ventilation panel attached to the casing, the at least one panel comprising a plurality of polygonal vents defined therein forming a vent array, each of the vents having at least two sidewalls integrally extending from the panel.
14. The electronic device enclosure as claimed in claim 13, wherein each of the

- vents in an inner portion of the vent array is surrounded by four of the sidewalls.
15. The electronic device enclosure as claimed in claim 14, wherein the sidewalls comprise first sidewalls and second sidewalls.
  16. The electronic device enclosure as claimed in claim 15, wherein both the first sidewalls and the second sidewalls are perpendicular to the base plate.
  17. The electronic device enclosure as claimed in claim 15, wherein the first sidewalls are perpendicular to the second sidewalls.
  18. The electronic device enclosure as claimed in claim 14, wherein the sidewalls slantwisely and inwardly extend from respective sides of each of the vents and define a smaller upper opening therebetween.
  19. The electronic device enclosure as claimed in claim 13, wherein the polygonal vents are hexagon vents, and the at least two sidewalls comprises three sidewalls stamped from the base plate adjacent spaced three edges of the vents, respectively.
  20. The electronic device enclosure as claimed in claim 19, wherein each of the hexagon vents in an inner portion of the base plate is surrounded on spaced three sides by said three sidewalls formed therein and surrounded on the other three sides by other three sidewalls formed in three adjacent vents, respectively.